

PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

EPAS ID: PAT5685642

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
RYOHEI YUMOTO	06/13/2019
TOMOYA OOHIRAKI	06/11/2019
TAKESHI KITAHARA	06/13/2019
YOSHIYUKI NAGATOMO	06/13/2019
RECEIVING PARTY DATA	
Name:	MITSUBISHI MATERIALS CORPORATION
Street Address:	2-3, MARUNOUCHI 3-CHOME, CHIYODA-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	100-8117
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16488634
CORRESPONDENCE DATA	
Fax Number:	(617)227-4420
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	2024787385
Email:	akiko.angelov@lockelord.com
Correspondent Name:	LOCKE LORD LLP
Address Line 1:	P.O. BOX 55874
Address Line 4:	BOSTON, MASSACHUSETTS 02205
ATTORNEY DOCKET NUMBER:	1420149.682US9
NAME OF SUBMITTER:	JAMES E. ARMSTRONG IV
SIGNATURE:	/James E. Armstrong IV/
DATE SIGNED:	08/26/2019
This document serves as an Oath/Declaration (37 CFR 1.63).	
Total Attachments: 8	
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**COMBINED ASSIGNMENT & DECLARATION
FOR UTILITY OR DESIGN PATENT APPLICATIONS**

ASSIGNMENT

THIS ASSIGNMENT, made by (1) Ryouhei YUMOTO; (2) Tomoya OOHIRAKI; (3) Takeshi KITAHARA; and (4) Yoshiyuki NAGATOMO; residing at (1) to (4) c/o MITSUBISHI MATERIALS CORPORATION, Central Research Institute, 600, Kitabukuro-cho 1-chome, Omiya-ku, Saitama-shi, Saitama 330-8508 Japan; respectively;

WHEREAS, Assignors have invented certain new and useful improvements in

METHOD FOR PRODUCING INSULATING CIRCUIT SUBSTRATE WITH HEAT SINK

set forth in a Patent application for Letters Patent of the United States, filed herewith; and

WHEREAS, MITSUBISHI MATERIALS CORPORATION, a corporation organized under and pursuant to the laws of Japan having its principal place of business at 2-3, Marunouchi 3-chome, Chiyoda-ku, Tokyo 100-8117 Japan (hereinafter referred to as Assignee), is desirous of acquiring the entire right, title and interest in and to said inventions and said Application for Letters Patent of the United States, and in and to any Letters Patent of the United States to be obtained therefore and thereon.

NOW, THEREFORE, in consideration of Ten Dollar (\$10.00) and other good and sufficient consideration, the receipt of which is hereby acknowledged, Assignors have sold, assigned, transferred and set over, and by these presents do sell, assign, transfer and set over, unto Assignee, its successors, legal representatives and assigns, the entire right, title and interest in and to the above-mentioned inventions and application for Letters Patent, and in and to any and all direct and indirect divisions, continuations and continuations-in-part of said application, and any and all Letters Patent in the United States and all foreign countries which may be granted therefore and thereon, and reissues, reexaminations and extensions of said Letters Patent, and all rights under the International Convention for the Protection of Industrial Property, the same to be held and enjoyed by Assignee, for its own use and benefit and the use and benefit of its successors, legal representatives and assigns, to the full end of the term or

terms for which Letters Patent may be granted and/or extended, as fully and entirely as the same would have been held and enjoyed by Assignors, had this sale and assignment not been made.

AND for the same consideration, Assignors hereby represent and warrant to Assignee, its successors, legal representatives and assigns, that, at the time of execution and delivery of these presents, except for any rights, titles and/or interests that have arisen to Assignee under law or that have already been transferred to Assignee, Assignors are the sole and lawful owners of the entire right, title and interest in and to the said inventions and application for Letters Patent above-mentioned, and that the same are unencumbered and that Assignors have good and full right and lawful authority to sell and convey the same in the manner herein set forth.

AND for the same consideration, Assignors hereby covenant and agree to and with Assignee, its successors, legal representatives and assigns, that Assignors will sign all papers and documents, take all lawful oaths and do all acts necessary or required to be done for the procurement, maintenance, enforcement and defense of any Letters Patent and applications for Letters Patent for said inventions, without charge to Assignee, its successors, legal representatives and assigns, whenever counsel of Assignee, or counsel of its successors, legal representatives and assigns, shall advise: that any proceeding in connection with said inventions, or said Patent application for Letters Patent, or any proceeding in connection with any Letters Patent or applications for Letters Patent for said inventions in any country, including but not limited to interference proceedings, is lawful and desirable; or, that any division, continuation or continuation-in-part of any application for Letters Patent, or any reissue, reexamination or extension of any Letters Patent, to be obtained thereon, is lawful and desirable.

AND Assignors hereby request the Commissioner for Patents and Trademarks to issue said Letters Patent of the United States to Assignee, as Assignee of said inventions and the Letters Patent to be issued thereon, for the sole use and benefit of Assignee, its successors, legal representatives and assigns.

AND Assignors acknowledge an obligation of assignment of this invention to Assignee at the time the invention was made.

DECLARATION

As a below named inventor, I hereby declare that:

This declaration is directed to the patent application entitled:

METHOD FOR PRODUCING INSULATING CIRCUIT SUBSTRATE WITH HEAT SINK

the specification of which is attached hereto.

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I have reviewed and understand the contents of the above-identified application.

I am aware of the duty to disclose to the Office all information known to me to be material to patentability as defined in 37 C.F.R. 1.56.

I hereby acknowledge that any willful false statement made in this Declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

In the event that the filing date and/or Application No. are not entered above at the time I execute this document, and if such information is deemed necessary, I hereby authorize and request the attorneys/agent(s) at Locke Lord LLP, P.O. Box 55874, Boston, Massachusetts 02205, to insert the filing date and/ or Application No. of said application into this document.

Date: 13/June/2019

Signature: Ryouhei Yumoto
Ryouhei YUMOTO

Date: _____

Signature: _____
Tomoya OOHIRAKI

Date: 13. June. 2019

Signature: Takeshi Kitahara
Takeshi KITAHARA

Date: 13. June 2019

Signature: Yoshiyuki Nagatomo
Yoshiyuki NAGATOMO

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to any and all direct and indirect divisions, continuations and continuations-in-part of said
application, and any and all Letters Patent in the United States and all foreign countries which
may be granted therefore and thereon, and reissues, reexaminations and extensions of said
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and benefit of its successors, legal representatives and assigns, to the full end of the term or

terms for which Letters Patent may be granted and/or extended, as fully and entirely as the same would have been held and enjoyed by Assignors, had this sale and assignment not been made.

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Date: _____

Signature: _____
Ryouhei YUMOTO

Date: June 11th, 2019

Signature: Tomoya OOHIRAKI
Tomoya OOHIRAKI

Date: _____

Signature: _____
Takeshi KITAHARA

Date: _____

Signature: _____
Yoshiyuki NAGATOMO